

REV.	DESCRIPTION	DATE	DRAWN
A	New	05.12.2013	Ronny
D	add 10 P & 20P	10.12.2018	RH
E	Design and solder feet improvement	18.12.2018	RH
F	take away -> 82 = 8.20mm	23.01.2019	Ronny
G	Remove Plating Option 95 & 9L5, Add view X	23.01.2020	Cheng

Order Code
MBC-xxx-QMV82-xx/11E

Plating

- 96 = Tin/10µ" Gold
- 97 = Tin/15µ" Gold
- 98 = Tin/30µ" Gold

No. of Pins	Dimension mm				
	A	B	C	D	E
012	12.70	9.57	6.35	8.57	10.77
016	15.24	12.11	8.89	11.11	13.31
020	17.78	14.65	11.43	13.65	15.85
026	21.59	18.46	15.24	17.46	19.66
030	24.13	21.00	17.78	20.00	22.20
032	25.40	22.27	19.05	21.27	23.47
040	30.48	27.35	24.13	26.35	28.55
050	36.83	33.70	30.48	32.70	34.90
068	48.26	45.13	41.91	44.13	46.33
080	55.88	52.75	49.53	51.75	53.95
100	68.58	65.45	62.23	64.45	66.65

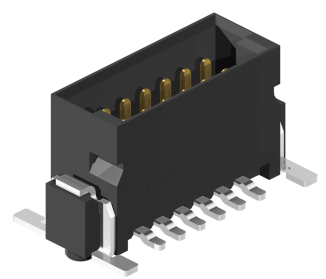
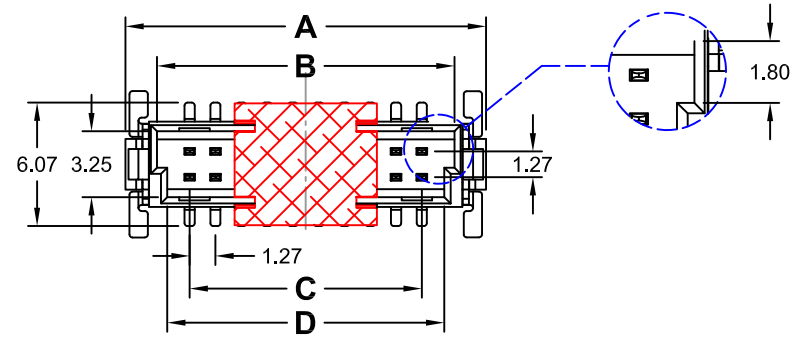


Material

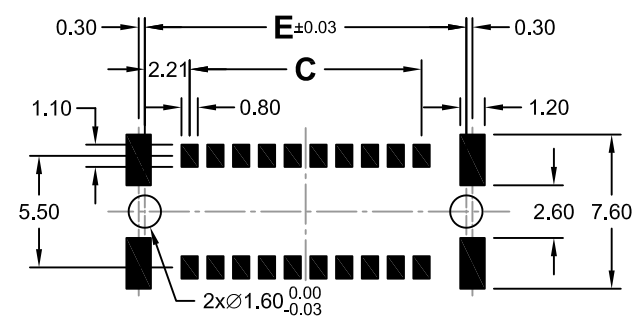
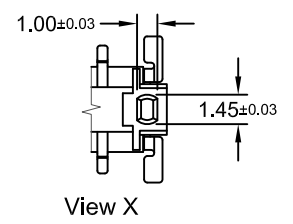
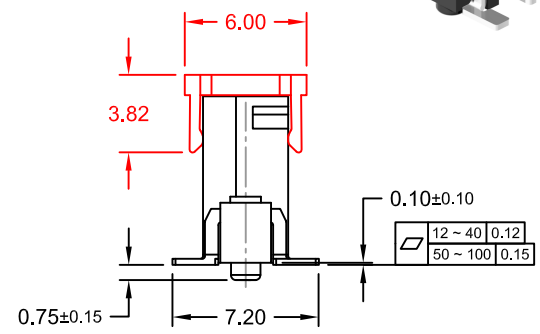
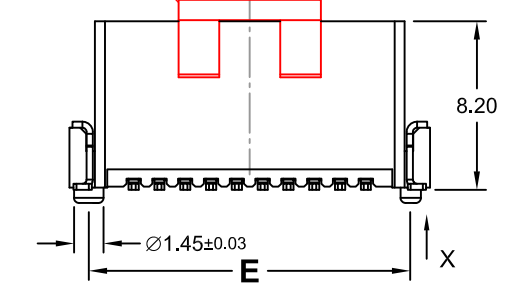
Contact: Copper Alloy
 Plating: Tin on solder, Gold on contact area
 Insulator: High Temperature Thermoplastic (black)
 UL 94V-0

Operating temperature: -55°C to +125°C
 Processing temperature: +260°C +0/-5°C
 for 5 seconds

Packing: Reel with Pickup Cap



PickUp Cap
 10-20 Pin 7.00
 26-100Pin 16.00

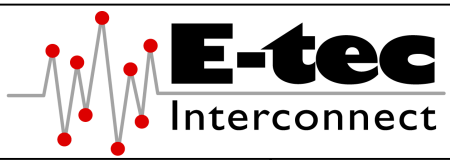


Recommended PCB Layout Top View
 (Tolerance ±0.05)

Specifications

Electrical
 Current rating: 0.5 ~ 1.0A
 Insulation resistance: 10000MΩ min.
 Contact resistance: 25mΩ max.
 Withstanding voltage: 500V

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UNIT mm	GENERAL TOLERANCE		DRAWN Ronny	DATE 10.01.2017	DWG. NO. MBC-QMV82/11	SHEET 1/1	
	X.° ±	X. ±					
	SCALE Free	.X° ±	.X ±	CHECK Cheng	DATE 23.01.2020	SERIES NO. MBC-xxx-QMV82-xx/11E	REV. G
	APPROVE Fagi	.XX° ±	.XX ± 0.25	DATE 23.01.2020			
	.XXX° ±	.XXX ±					

Multi BUS/Backplane Connector
Q-Type Male SMT vertical
 1.27mm Pitch - Height 8.20mm
Compatible to ERNI INTERact® Series SMC Type